

STRUCTURE OF HEAT SLUG-EQUIPPED PACKAGES AND THE PACKAGING METHOD OF THE SAME

Abstract of the Disclosure

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The package includes a chip located on a substrate with signal transferring device electrically connected between them. Solder balls connect the substrate and thus electrically connect the substrate to external circuits. Molding compound is covered to protect the chip and signal transferring means. The heat-slug is capped over the molding compound through a conductive glue. All area of the upper surface of the heat-slug is exposed to the ambient to improve the capability of spreading heat.

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